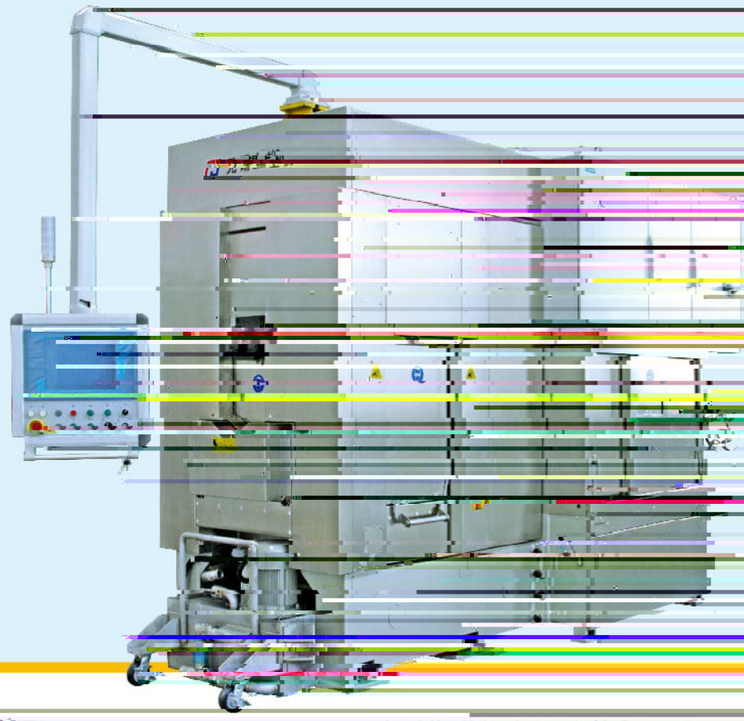
WSK000
蓝宝石切片机
WSK000 Sapphire Slicing Machine



技术规格参数 Specifications and Technical Parameters

规格 Specification	8inches（max）
长度 Length	500mm
厚度 Thickness	>0.2mm

主要参数 Main Parameters

导轮直径 Guide wheel diameter	320mm
导轮轴距 Guide wheelbase	440mm
导轮长度 Guide wheel length	550mm
线速度 Line speed	0-30m/s
进给速率 Feed rate	0.05mm-2.00mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	forward or reverse cutting/two-way cutting
存储线直径 Storage wire diameter	≤0.18mm
水箱容量 Water tank capacity	220L

能源参数 Energy Parameters

电源连接 Power connection	220/380V，3PE，50HZ
平均功率 Average power	30KW
总装机容量 Mounting power	12.2 17.2KW

外形尺寸 Overall Size

机床外形尺寸（长*宽*高） Machine tool dimensions (L*W*H)	4000*2500*3000mm
机床重量 Weight	~12000kg

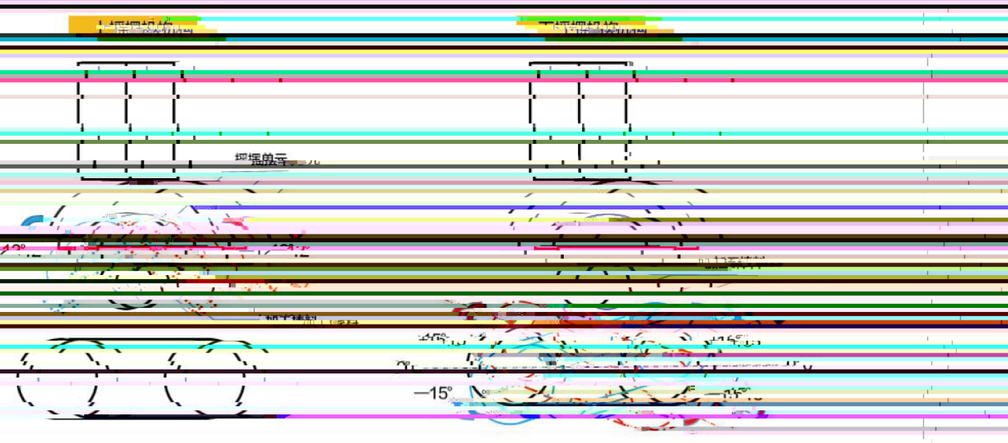
设备用途与性能特点 Equipment Purpose and Features

- 本机床用于各种脆硬材料，如硅、锗、石英玻璃、陶瓷、蓝宝石晶体等的切割。
- 机床所有电器元件均采用国际知名品牌，保证机床的稳定性。
- 采用西门子切割技术的一体化PC和15"触摸屏。
- 电控柜配备独立温控系统，保证[illegible]
- 设备具备摇摆功能，双向交替切割与往复式单向切割均可选，可根据需要自由切换，能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅3个滑轮），减少了线张力的波动。

Equipment Purpose and Features

- This machine is used for automatically cutting hard and brittle materials using diamond tools to cut silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components adopt international well-known brands to ensure the stability of the machine.
- Apply integrated PC of SIEMENS simulation controlling system, 15" touch screen.
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment oscillation function can be selected as needed, and the reciprocating single-direction cutting function can be selected as needed. The oscillation function unit optimizes the performance of diamond wire cutting, improves the cutting line, and improves the wafer quality.
- Minimal design number of pulleys (only 3 pulleys), reducing line tension fluctuations caused by line distortion and fatigue.

示意图 Sketch



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As products are constantly improved, the specifications, parameters, pictures, etc. of the products described in this data may be changed without notification, we reserve the right to explain.